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Vishay Siliconix

# Automotive N-Channel 60 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.006			
I <sub>D</sub> (A)	119			
Configuration	Single			
Package	TO-220			



## **FEATURES**

- TrenchFET® power MOSFET
- Package with low thermal resistance
- AEC-Q101 qualified d
- 100 % R<sub>a</sub> and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



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N-Channel MOSFET	o s

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V <sub>DS</sub>	60	V	
Gate-Source Voltage		$V_{GS}$	± 20	V	
Continuous Drain Current	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	119	A	
Continuous Drain Cufferit	T <sub>C</sub> = 125 °C		68		
Continuous Source Current (Diode Condu	ction) a	I <sub>S</sub>	120		
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	480		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	65		
Single Pulse Avalanche Energy	L = U.1 IIII	E <sub>AS</sub>	211	mJ	
Maximum Power Dissipation b	T <sub>C</sub> = 25 °C	В	175	W	
Maximum Fower Dissipation 5	T <sub>C</sub> = 125 °C	$P_{D}$	56	VV	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount <sup>c</sup>	$R_{thJA}$	40	°C/W		
Junction-to-Case (Drain)		$R_{thJC}$	0.88	C/VV		

### **Notes**

- a. Package limited.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. Parametric verification ongoing.



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PARAMETER Static  Drain-Source Breakdown Voltage Gate-Source Threshold Voltage Gate-Source Leakage  Zero Gate Voltage Drain Current  On-State Drain Current a	V <sub>DS</sub> V <sub>GS(th)</sub>	TES	T CONDITIONS	MIN.	TYP.	MAN				
Drain-Source Breakdown Voltage Gate-Source Threshold Voltage Gate-Source Leakage Zero Gate Voltage Drain Current						MAX.	UNIT			
Gate-Source Threshold Voltage  Gate-Source Leakage  Zero Gate Voltage Drain Current			Static							
Gate-Source Leakage  Zero Gate Voltage Drain Current	V <sub>GS(th)</sub>	$V_{GS}$	$V_{GS} = 0$ , $I_D = 250 \mu A$		-	-	V			
Zero Gate Voltage Drain Current		V <sub>DS</sub> =	: V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.5	3.0	3.5	V			
<u> </u>	$I_{GSS}$	V <sub>DS</sub> =	$0 \text{ V}, \text{ V}_{GS} = \pm 20 \text{ V}$	=	-	± 100	nA			
<u> </u>		$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V	1	-	1				
On-State Drain Current <sup>a</sup>	$I_{DSS}$	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$	1	-	50	μA			
On-State Drain Current <sup>a</sup>		$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 175 °C	-	-	250				
	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	120	-	-	Α			
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A	-	0.0045	0.0060				
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C	-	-	0.0104	Ω			
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C	-	-	0.0129				
Forward Transconductance b	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A		-	94	-	S			
Dynamic <sup>b</sup>										
Input Capacitance	C <sub>iss</sub>			-	5196	6495				
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	-	708	885	pF			
Reverse Transfer Capacitance	C <sub>rss</sub>	]		-	336	420				
Total Gate Charge <sup>c</sup>	Qg			-	96.5	145				
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 30 \text{ V}, I_D = 75 \text{ A}$	-	24.6	-	nC			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>	]		-	27.2	-				
Gate Resistance	$R_g$		f = 1 MHz	0.3	1	1.7	Ω			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	16	24				
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, \text{ R}_{L} = 0.4 \Omega$ $I_{D} \cong 75 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_{g} = 1 \Omega$		-	14	21				
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	34	51	ns			
Fall Time <sup>c</sup>	t <sub>f</sub>			-	9	14				
Source-Drain Diode Ratings and Characteristics <sup>b</sup>										
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	480	Α			
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 75 A, V <sub>GS</sub> = 0		-	0.9	1.5	V			

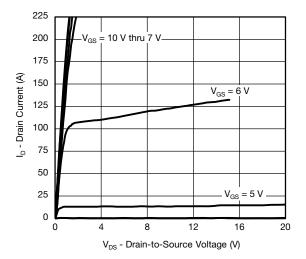
#### **Notes**

- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

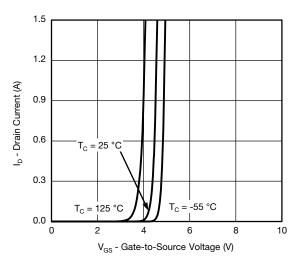
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



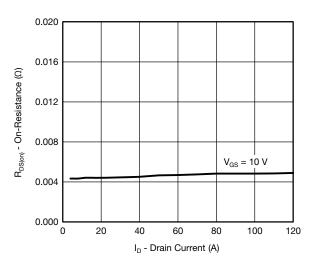
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



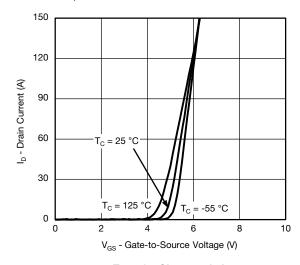
#### **Output Characteristics**



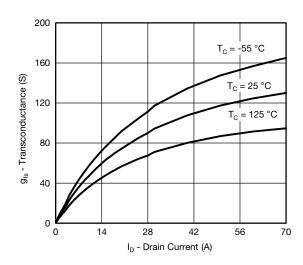
## Transfer Characteristics



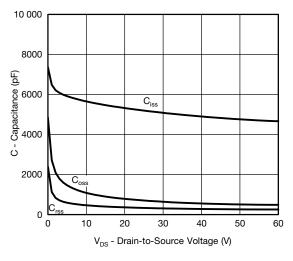
On-Resistance vs. Drain Current



### **Transfer Characteristics**



### Transconductance

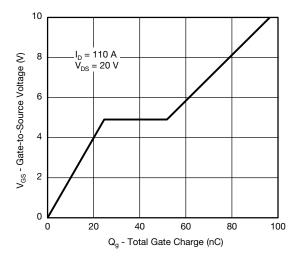


Capacitance

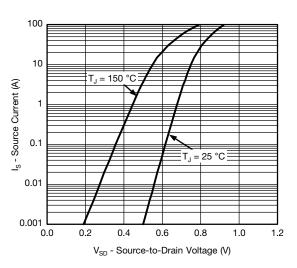
For technical questions, contact: automostechsu



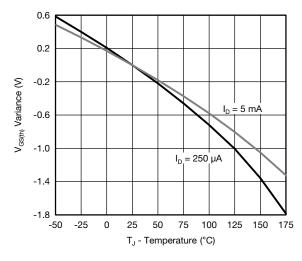
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



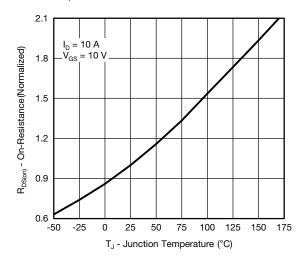
**Gate Charge** 



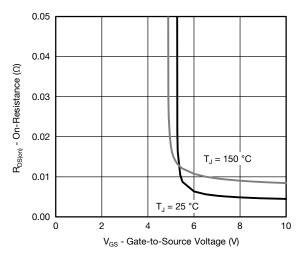
**Source Drain Diode Forward Voltage** 



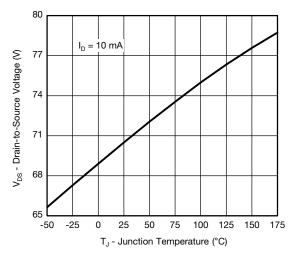
**Threshold Voltage** 



On-Resistance vs. Junction Temperature



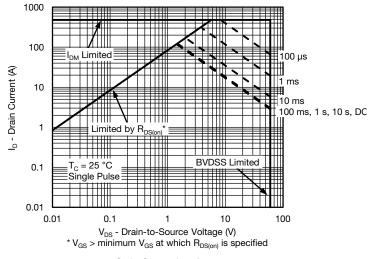
On-Resistance vs. Gate-to-Source Voltage



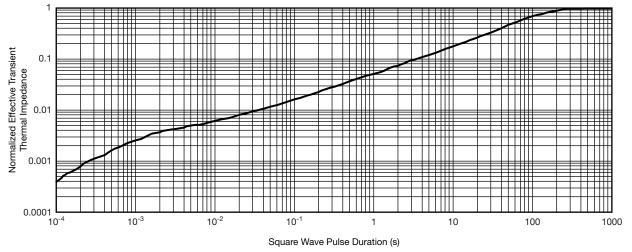
Drain Source Breakdown vs. Junction Temperature



## **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



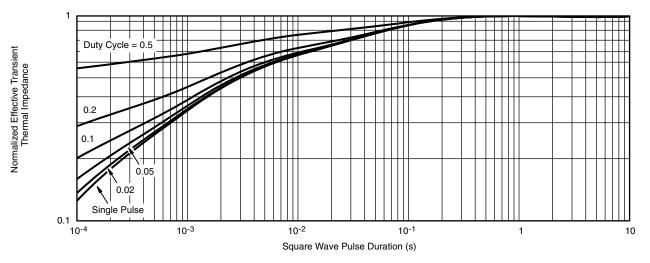
## Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



## THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg262853">www.vishay.com/ppg262853</a>.



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REVISION	REVISION HISTORY <sup>a</sup>				
REVISION	DATE	DESCRIPTION OF CHANGE			
В	04-Aug-15	Revised R <sub>g</sub> minimum limit			

#### Note

a. As of April 2014



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## **TO-220**

Ordering codes for the SQ rugged series power MOSFETs in the TO-220 package:

DATASHEET PART NUMBER	OLD ORDERING CODE <sup>a</sup>	NEW ORDERING CODE
SQP100N04-3m6	-	SQP100N04-3M6_GE3
SQP100P06-9m3L	-	SQP100P06-9M3L_GE3
SQP120N06-06	-	SQP120N06-06_GE3
SQP120N06-3m5L	SQP120N06-3M5L-GE3	SQP120N06-3M5L_GE3
SQP120N10-09	SQP120N10-09-GE3	SQP120N10-09_GE3
SQP120N10-3m8	SQP120N10-3M8-GE3	SQP120N10-3M8_GE3
SQP25N15-52	-	SQP25N15-52_GE3
SQP50N06-09L	SQP50N06-09L-GE3	SQP50N06-09L_GE3
SQP50P03-07	SQP50P03-07-GE3	SQP50P03-07_GE3
SQP60N06-15	SQP60N06-15-GE3	SQP60N06-15_GE3
SQP90P06-07L	SQP90P06-07L-GE3	SQP90P06-07L_GE3

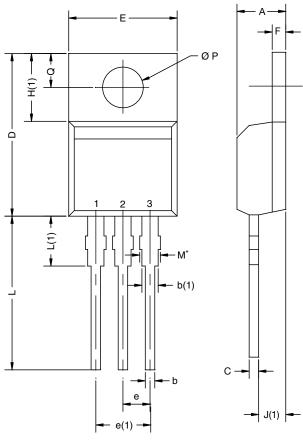
#### Note

a. Old ordering code is obsolete and no longer valid for new orders



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## **TO-220AB**



	1	
		D2

	MILLIN	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
D2	12.19	12.70	0.480	0.500	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471					

### Note

 $^{\star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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Revision: 02-Oct-12 Document Number: 91000

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614233C 648584F IRFD120 JANTX2N5237 FCA20N60\_F109 FDZ595PZ 2SK2545(Q,T) 405094E 423220D TPCC8103,L1Q(CM MIC4420CM-TR VN1206L SBVS138LT1G 614234A 715780A NTNS3166NZT5G SSM6J414TU,LF(T 751625C BUK954R8-60E DMN3404LQ-7 NTE6400 SQJ402EP-T1-GE3 2SK2614(TE16L1,Q) 2N7002KW-FAI DMN1017UCP3-7 EFC2J004NUZTDG ECH8691-TL-W FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE221 NTE2384 NTE2903 NTE2941 NTE2945 NTE2946 NTE2960 NTE2967 NTE2969 NTE2976 NTE455 NTE6400A NTE2910 NTE2916 NTE2956 NTE2911 DMN2080UCB4-7 TK10A80W,S4X(S SSM6P69NU,LF DMP22D4UFO-7B